SGS-THOMSON MICROELECTRONICS

SD1542-04

RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- DESIGNED FOR HIGH POWER PULSED IFF
- 600 WATTS (min.) IFF 1030/1090 MHz
- REFRACTORY GOLD METALLIZATION
- 6.0 dB MIN. GAIN
- BALLASTING AND LOW THERMAL
 REISTANCE FOR RELIABILITY AND RUGGEDNESS
- 30:1 LOAD VSWR CAPABILITY AT SPECIFIED OPERATING CONDITIONS
- INPUT MATCHED, COMMON BASE CONFIGURATION



DESCRIPTION

The SD1542-04 is a hermetically sealed, gold metallized, silicon NPN power transistor. The SD1542-04 is designed for applications requiring high peak power and low duty cycles such as IFF. The SD1542-04 is packaged in a hermetic metal/ceramic package with internal input matching, resulting in improved broadband performance and low thermal reistance.

led, gold me-The SD1542ng high peak as IFF. The tric metal/cematching, reprmance and 1. Collector 3. Emitter 2. Base 4. Base

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$)

| Symbol | Parameter | Value | Unit V | |
|------------------|---------------------------|--------------|-----------|--|
| Vсво | Collector-Base Voltage | 65 | | |
| VCES | Collector-Emitter Voltage | 65 | V | |
| VEBO | Emitter-Base Voltage | 3.5 | V | |
| lc | Device Current | 40 | А | |
| PDISS | Power Dissipation | 1350 | W | |
| TJ | Junction Temperature | +200 | °C | |
| T _{STG} | Storage Temperature | – 65 to +150 | °C | |

THERMAL DATA

| R _{TH(j-c)} Junction-Case Thermal Resistance | 0.06 | °C/W |
|---|------|------|
|---|------|------|



SD1542-04

ELECTRICAL SPECIFICATIONS ($T_{case} = 25^{\circ}C$)

STATIC

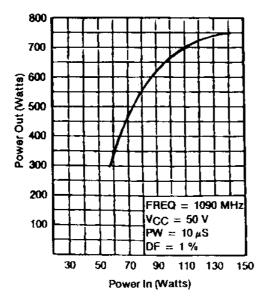
| Symbol | Test Conditions | | Value | | | Unit | |
|-------------------|-----------------|-----------------|-------|------|------|------|----|
| | | М | lin. | Тур. | Max. | om | |
| ВУсво | $I_C = 25 mA$ | $I_E = 0 m A$ | e | 65 | _ | | V |
| BV _{EBO} | $I_E = 10 mA$ | $I_{C} = 0 m A$ | 3 | 3.5 | _ | _ | V |
| ICES | $V_{CE} = 50V$ | $I_E = 0 m A$ | - | | | 35 | mA |
| h _{FE} | $V_{CE} = 5V$ | $I_C = 1A$ | | 5 | _ | 200 | |

DYNAMIC

| Symbol | Test Conditions | | | Value | | | |
|--------|-----------------|--------------------------|---------------------------------|-------|------|------|------|
| Symbol | Test conditions | | | Min. | Тур. | Max. | Unit |
| Pout | f = 1090 MHz | $P_{IN} = 150 \text{ W}$ | $V_{\text{CE}} = 50 \ \text{V}$ | 600 | — | _ | W |
| GP | f = 1090 MHz | $P_{IN} = 150 \text{ W}$ | $V_{CE} = 50 V$ | 6.0 | — | | dB |

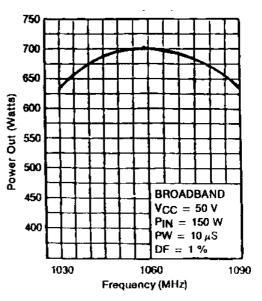
Note: Pulse Width = 10μ Sec, Duty Cyle = 1%

TYPICAL PERFORMANCE



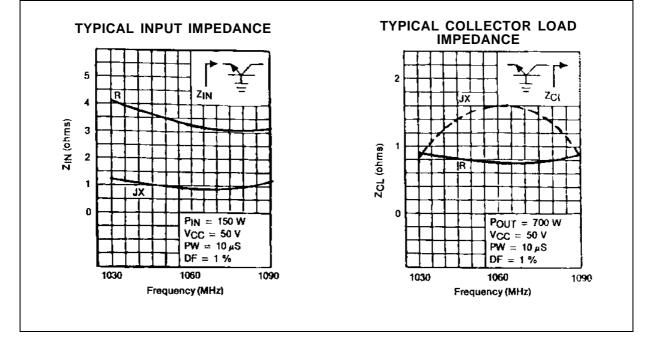
POWER OUTPUT vs POWER INPUT

POWER OUTPUT vs FREQUENCY



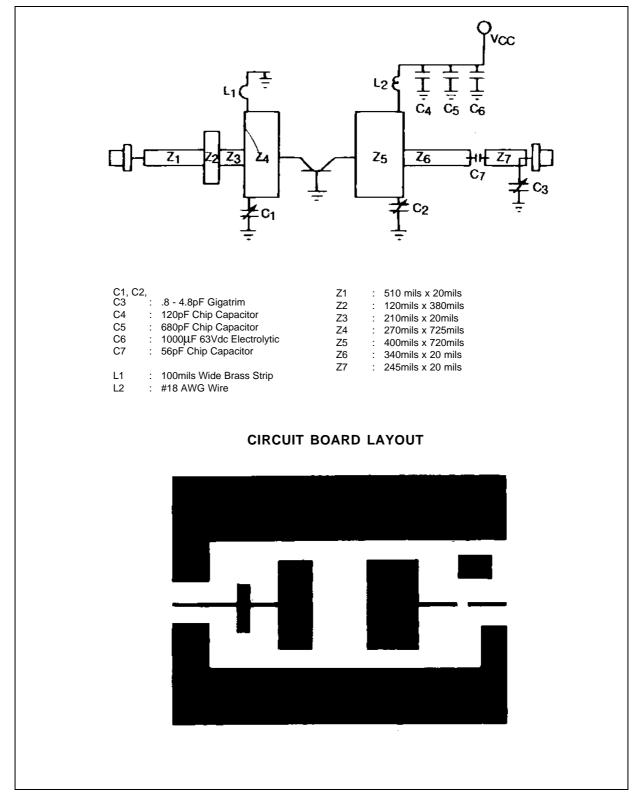


IMPEDANCE DATA



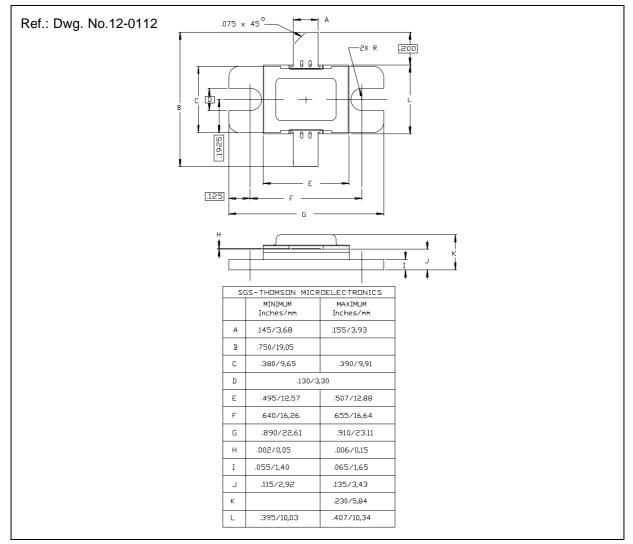


TEST CIRCUIT





PACKAGE MECHANICAL DATA



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